

Then in the 60's, the CMM hit the scene, man!

- CMMs allowed versatile, high accuracy measurements of geometry
- Could be used (almost) in-line as part of a controlled manufacturing process



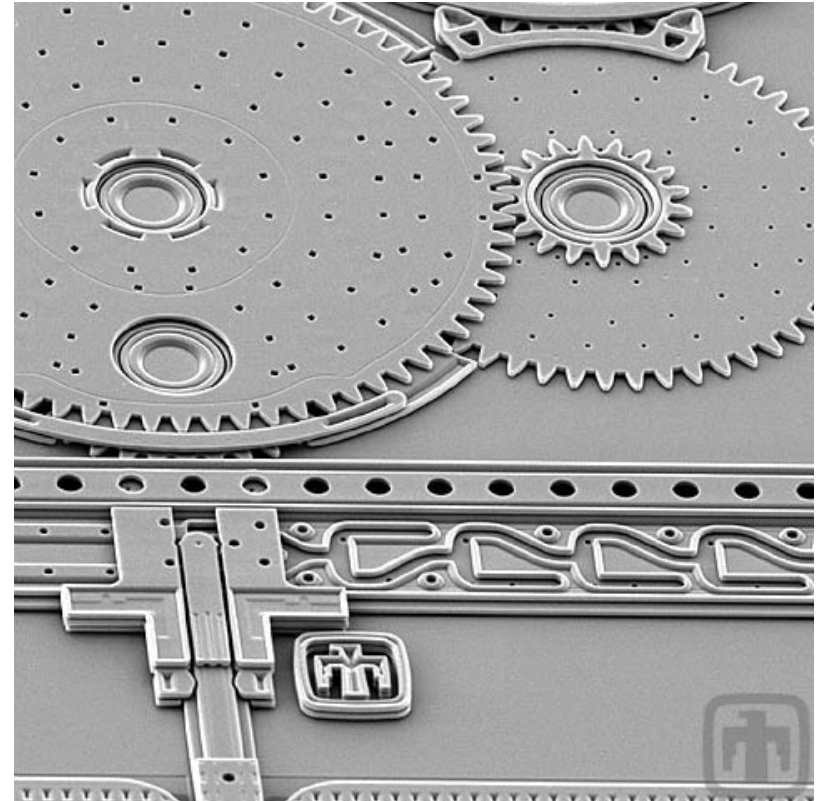
In the 70's and 80's there was the “CMM revolution”



- CMMs became integral part of manufacture
- Joined by CNC machining, CAD, in-line metrology, robotic handling, *etc.*

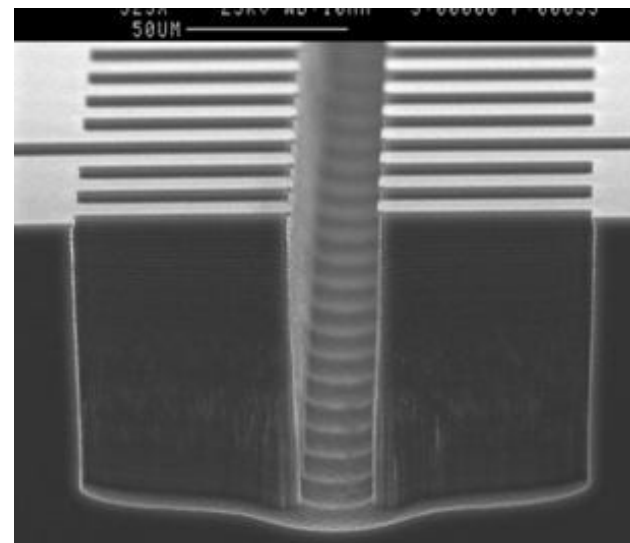
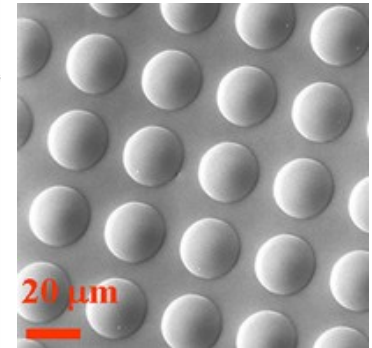
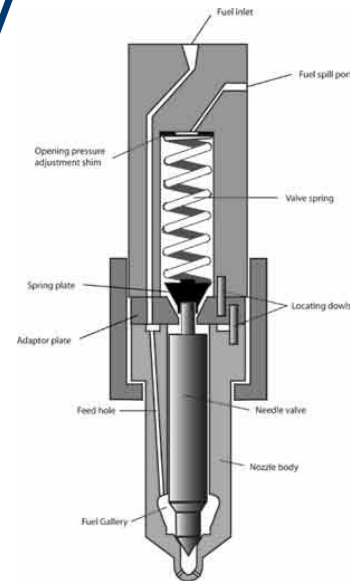
The 90's up to now – things started to shrink...

- Silicon electronic processes were applied to mechanical devices (MEMS)
- Products and components started to shrink
- Benefits include: lighter weight, better portability, less energy consumption, efficiency, more functionality, *etc.*



“True-3D” micro-metrology

- Modern manufacturing involves 3D integration of 3D micro-parts
- Have you ever taken apart your mobile telephone?
- Small optics, micro-mirrors
- Micro-fluidic components, lab-on-a-chip
- Medical devices
- MEMS structures
- Ink-jet/diesel injectors
- Small parts with ever-decreasing tolerances



Micro-coordinate metrology



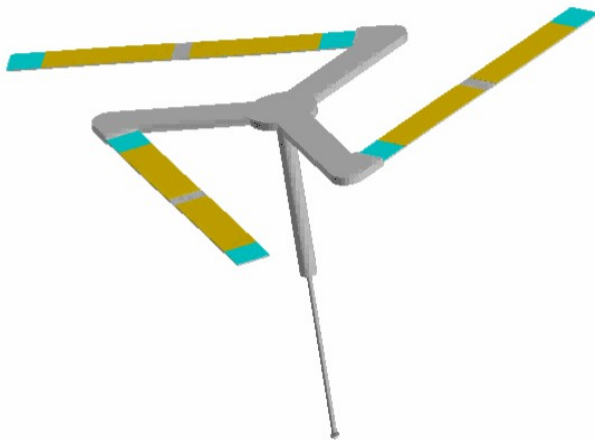
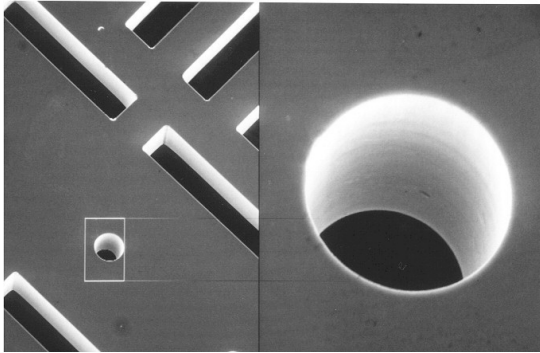
- As part of the TSB-funded CEMMNT project, NPL has procured a Zeiss F25 micro-CMM
- Range 100 mm x 100 mm x 100 mm
- Existing mechanical probes down to 0.3 mm diameter – need smaller
- Accuracy stated as 250 nm but this is conservative
- Probe resolution 10 nm
- Probing force a few μN
- Also incorporates an optical “vision” probe

So why not just shrink the probe?



- The laws of physics are not simply scaleable, there are jumps
- Aspect ratio becomes a problem
- Surface forces dominate over gravitational (stiction)
- Basically, things get too floppy

Micro-probe for micro-CMM



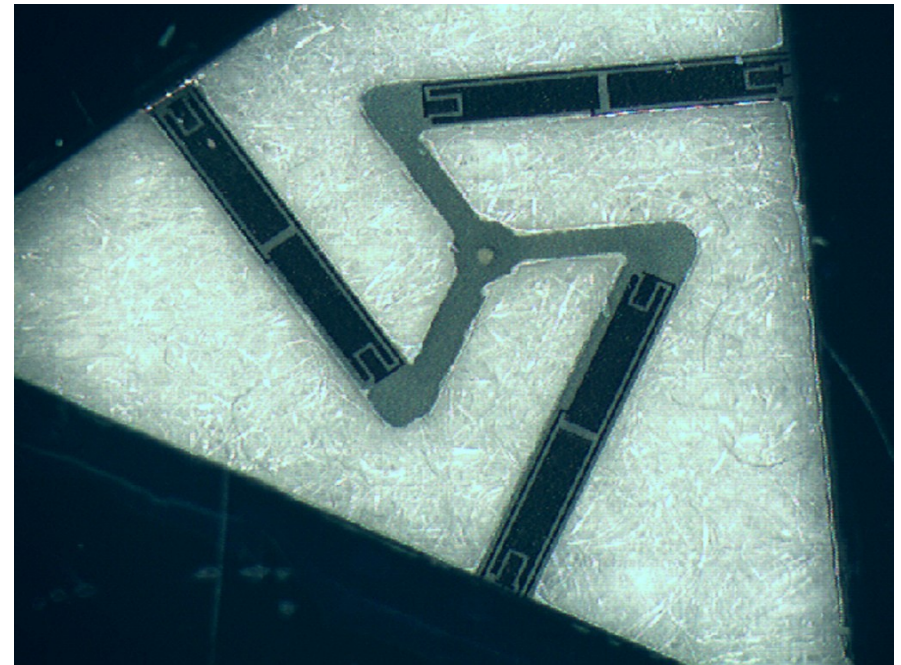
- Need for HAR structures, e.g. ink-jet nozzle, injectors, micro-fluidics, micro-optics
- Developing vibrating micro-CMM probe to interface with Zeiss F25 micro-CMM (1 mm length, $\phi < 50 \mu\text{m}$)
- F25 also has a vision probe – essential for location on part
- Collaboration with Cardiff, Greenwich, Cranfield, Cambridge, Nottingham and Taipei
- Applying for patent – licence to Zeiss

Working with so many academics
is a bit like...



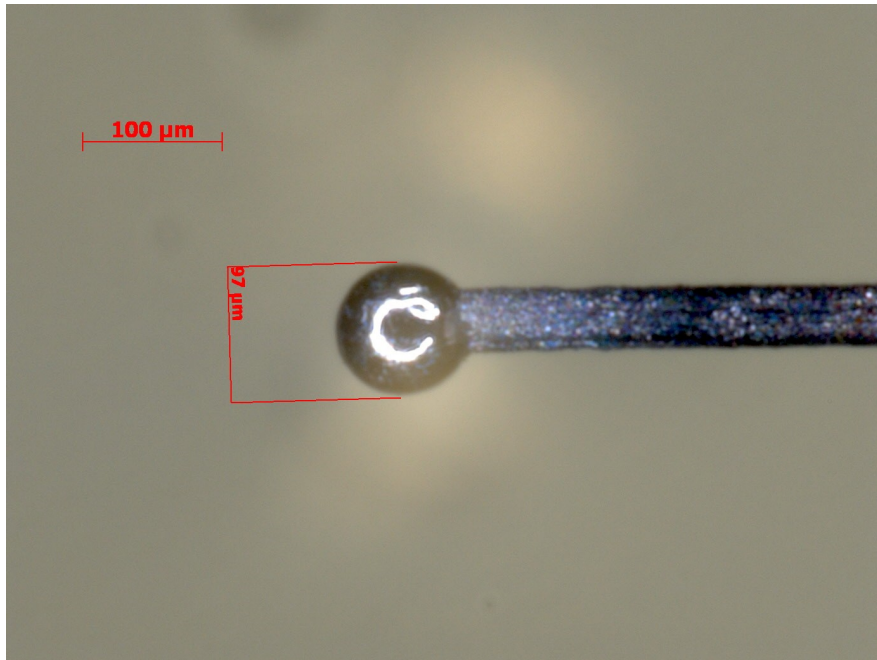
Prototype flexure manufacture

- Cranfield University
- PZT thin film layers on nickel using a silicon sacrificial substrate (removed using DRIE)
- Flexures now need electrical and mechanical testing and comparison with model



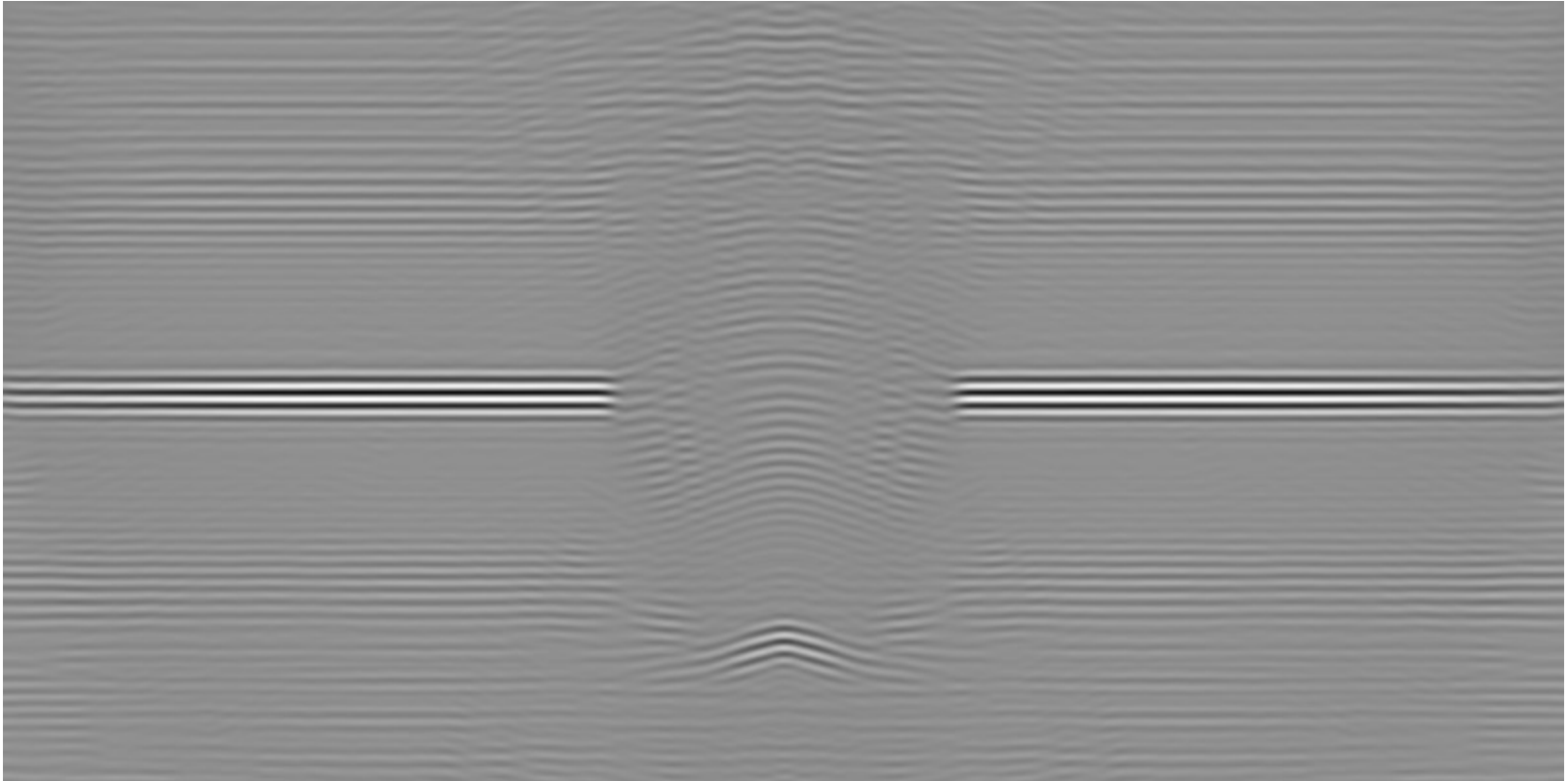
Stoyanov S *et al* 2008 Modelling and prototyping the conceptual design of a 3D CMM micro-probe *2nd ES/TC Greenwich*193-198

Micro-probe research



- Ball on stem manufactured using micro-EDM (Taipei, Cardiff)
- Ball direct machining led to rough and cracked end
- Attempting laser and etch methods to clean
- Ball also made by a melting and surface tension method

Interferogram 70 Degree V-groove



Illuminating and Observation $NA=0.5$

Inverse Problem

So we know we can produce interferograms that show the surface related problems of WLI using FEM/BEM to solve *the forward problem*.

Q. Can we calculate the surface accurately from one or more interferograms?

This is *the inverse problem*. Mathematically it is the solution that minimises an error function such as,

$$\text{Error} = \sum \left(E_S^m - E_S^{\text{calc.}} \right)^2$$

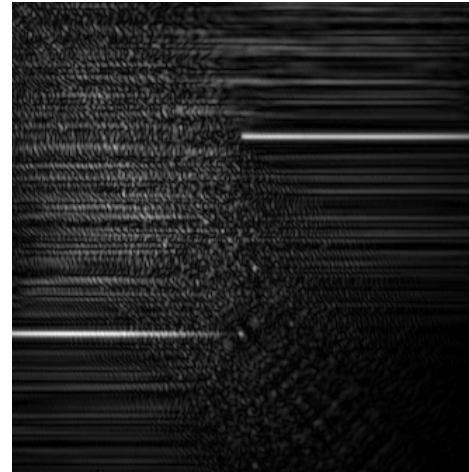
Measured scattered field

Calculated scattered field

A. Sometimes!

Optical trickery: the profile of a vertical wall (2 iterations)

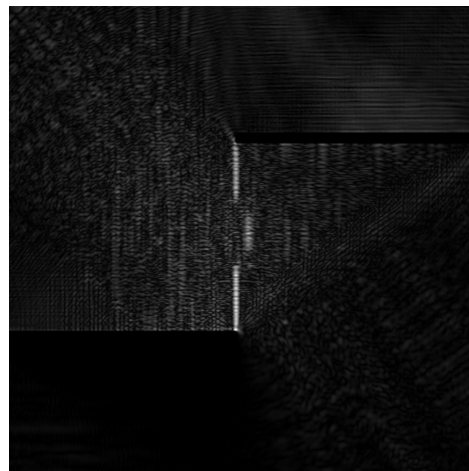
Object: 15 μm step with a 5 μm x 1 μm groove. Illumination from the top.



SWLI results (abs. value): top and bottom surfaces are found.



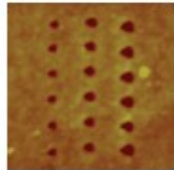
New object calculated from SWLI data using updated model shows the profile of the “vertical wall”



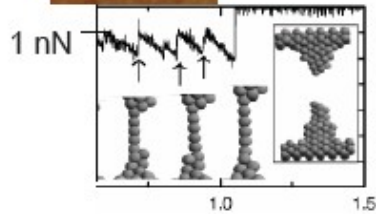
Low force ranges



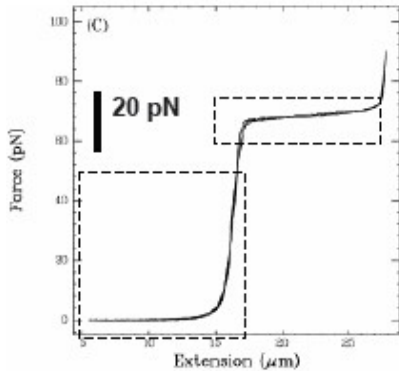
read head "lift" forces, 10 mN



Thin film hardness tests, 1 μ N-10 mN

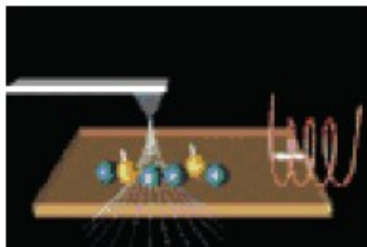


Bond rupture experiments, 1-2 nN



Single molecule pulling, 1-500 pN

Laser pointer, 6.6 pN



Unpaired electron spins, aN's?

10^{-2} N

10^{-6} N

10^{-10} N

10^{-14} N

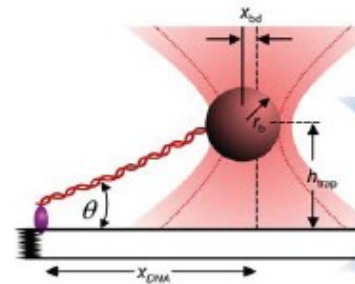
10^{-18}

mass balances

Instrumented indentation

atomic force microscopy

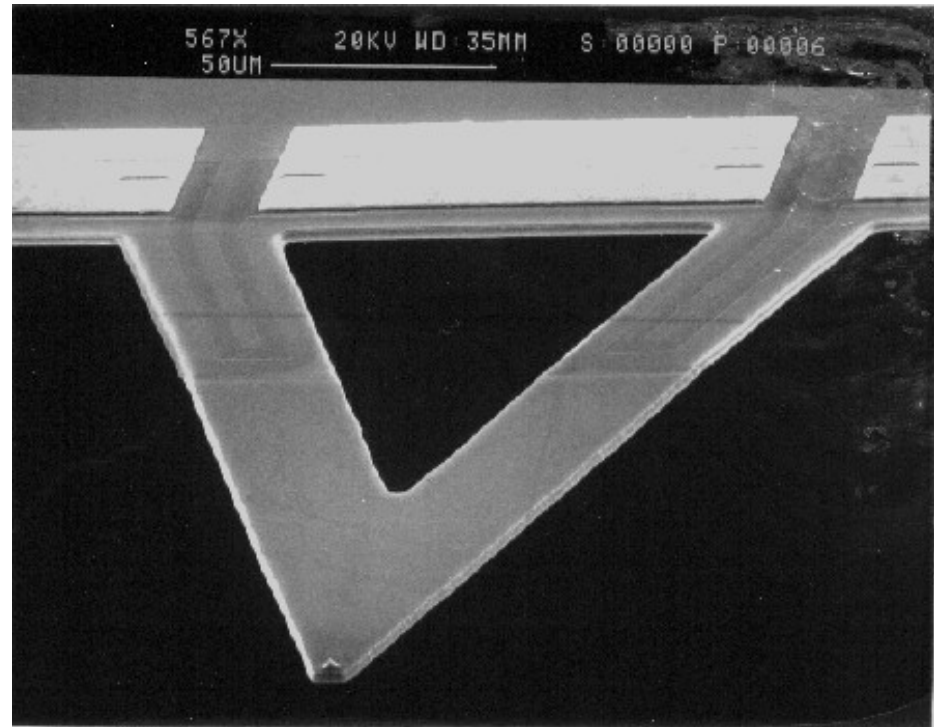
optical tweezers



magnetic resonance force microscopy

Who needs low force measurement?

- ◆ Surface texture measurement and small CMMs
- ◆ Scanning probe microscopy, especially AFM
- ◆ Materials characterisation using indentation techniques
- ◆ Micro-electromechanical systems sensors
- ◆ Biotechnology, e.g. measurement of protein elasticity
- ◆ Thruster technology, e.g. ion engines for space
- ◆ Nanomanipulation and assembly



Deadweights: the traditional force standard

- Weight of a known mass
- $1 \text{ nN} \equiv 0.1 \text{ } \mu\text{g} \equiv 0.1 \text{ mm} \times 0.1 \text{ mm} \times 5 \text{ } \mu\text{m Al}$
.... not practical!
- Suitable for comparison only at NMIs

- Mass defined in terms of a lump of metal – not ideal
- Not future proof

The NPL Primary Low Force Balance

- ◆ NPL has existing low force balance
- ◆ Range: 1 nN to 10 μN
- ◆ Resolution: 50 pN
- ◆ Need to compare to standard masses and radiation pressure

$$F = -\frac{1}{2}V^2 \frac{dC}{dz}$$

